

8mm (0.32") SINGLE DIGIT NUMERIC DISPLAY

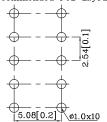
Features

- Low power consumption
- ullet Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant

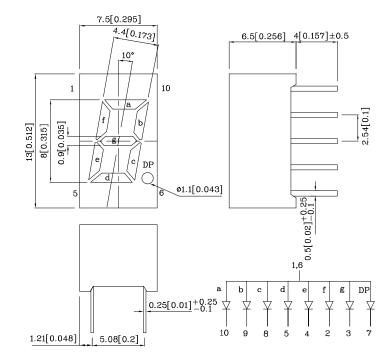




Recommended PCB Layout



Package Schematics



Notes

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.

2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	Yellow (GaAsP/GaP)	Unit		
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	P_D	75	mW	
Operating Temperature	T_{A}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	-0	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)	Yellow (GaAsP/GaP)	Unit	
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	1.95	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λΡ	λΡ 590*	
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	588*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	20	pF

Part Number	Emitting Color	Emitting Material	$\begin{array}{c} \text{Luminous Intensity} \\ \text{CIE127-2007*} \\ \text{(I}_{\text{F}}\text{=}10\text{mA)} \\ \text{ucd} \end{array}$		Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XDUY06A	Yellow	GaAsP/GaP	2200 900*	4990 1690*	590*	Common Anode, Rt.Hand Decimal.

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

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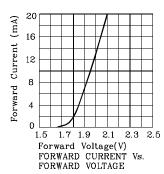


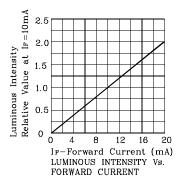


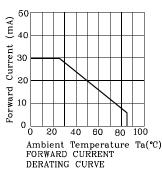
Yellow Relative Radiant Intensity Ta=25°C 0.5 450 500 600 650 700 750 wavelength ∧ (nm)

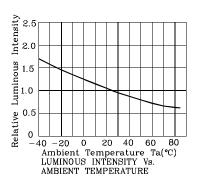
RELATIVE INTENSITY Vs. CIE WAVELENGTH

❖ Yellow

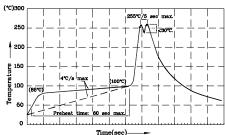








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- Notes:

 1. Recommend pre-heat temperature of 105°C or less (as measured w thermocouple attached to the LED pins) prior to immersion in the wave with a maximum solder bath temperature of 250°C

 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec max).

 3. Do not apply stress to the epoxy resin while the temperature is al 4.Fixtures should not incur stress on the component when mounting during soldering process.

 5.AGC 305 solder alloy is recommended.

 6. No more than one wave soldering pass.

 7. During wave soldering, the PCB top-surface temperature should be kept below 105°C. mmend pre-heat temperature of 105°C or less (as measured with a noccuple attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 260°C wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

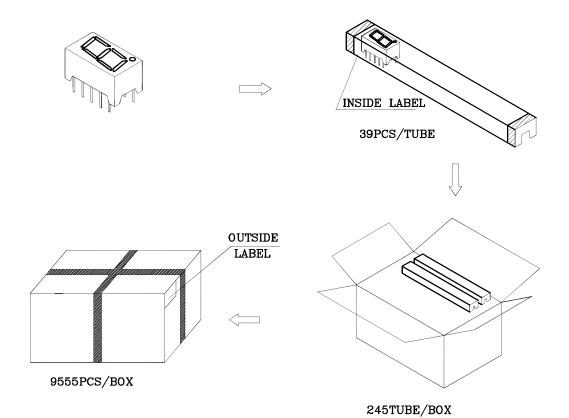
Note: Accuracy may depend on the sorting parameters.

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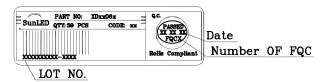




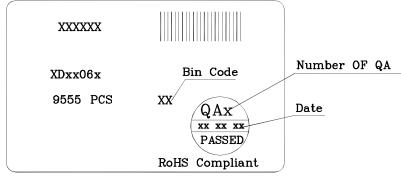
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



TERMS OF USE

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